Silicon NPN Epitaxial

# HITACHI

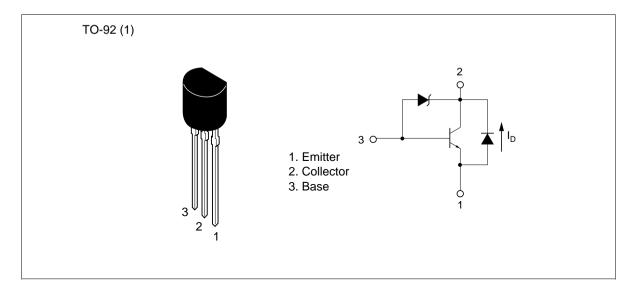
#### Application

Low frequency power amplifier

#### Features

- Build in zener diode for surge absorb.
- Suitable for relay drive with small power loss.

#### Outline





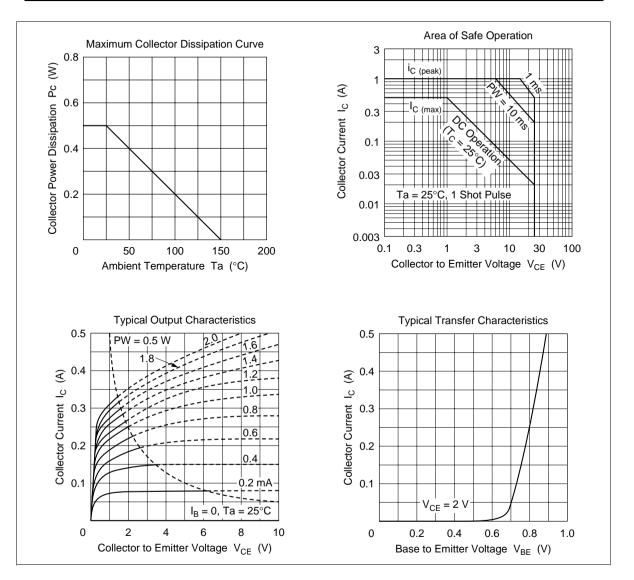
#### **Absolute Maximum Ratings** (Ta = $25^{\circ}$ C)

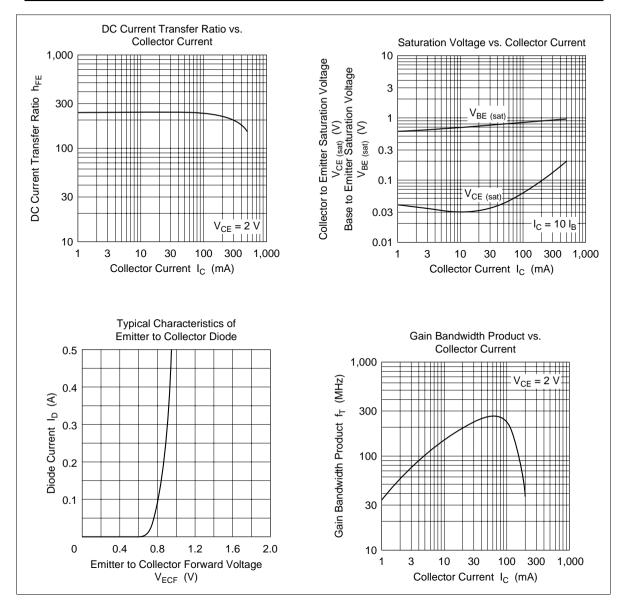
Item	Symbol	Ratings	Unit
Collector to base voltage	V <sub>CBO</sub>	25	V
Collector to emitter voltage	V <sub>CEO</sub>	25	V
Emitter to base voltage	V <sub>EBO</sub>	6	V
Collector current	Ι <sub>c</sub>	0.5	А
Collector peak current	İ <sub>C(peak)</sub>	1.0	А
E to C diode current	Ι <sub>D</sub>	0.5	А
Collector power dissipation	Pc	0.5	W
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55 to +150	°C

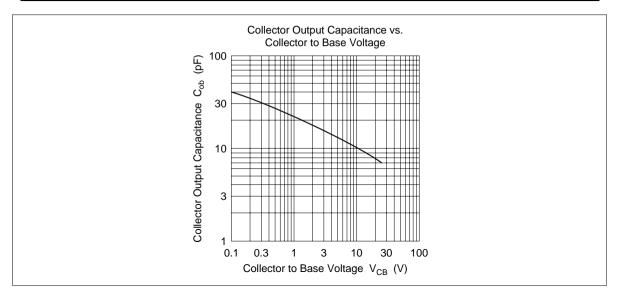
#### **Electrical Characteristics** (Ta = 25°C)

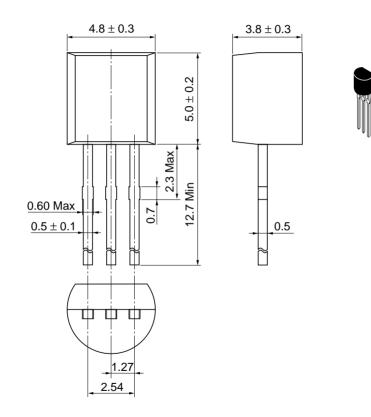
Item	Symbol	Min	Тур	Мах	Unit	Test conditions
Collector to base breakdown voltage	$V_{(BR)CBO}$	25	_	_	V	$I_{c} = 10 \ \mu A, \ I_{E} = 0$
Collector to emitter breakdown voltage	$V_{(BR)CEO}$	25	_	35	V	$I_c = 1 \text{ mA}, \text{ R}_{BE} = \infty$
Collector to emitter sustaining voltage	$V_{_{CEO(sus)}}$	26	—	36	V	$I_{c} = 0.5 \text{ A}, \text{ R}_{\text{BE}} = \infty,$ L = 20 mH
Emitter to base breakdown voltage	$V_{(BR)EBO}$	6	_	_	V	$I_{\rm E} = 10 \ \mu A, \ I_{\rm C} = 0$
Collector cutoff current	I <sub>CBO</sub>			0.2	μΑ	$V_{CB} = 20 \text{ V}, I_{E} = 0$
	I <sub>CEO</sub>		—	0.5	μΑ	$V_{ce}$ = 20 V, $R_{Be}$ = $\infty$
Emitter cutoff current	I <sub>EBO</sub>	_		0.2	μA	$V_{EB} = 5 V, I_{C} = 0$
DC current transfer ratio	h <sub>FE1</sub>	100	_	500		$V_{ce} = 2 \text{ V}, \text{ I}_{c} = 50 \text{ mA}^{*1}$
	h <sub>FE2</sub>	50				$V_{ce} = 2 V, I_c = 0.5 A^{*1}$
Collector to emitter saturation voltage	$V_{\text{CE(sat)}}$		_	0.5	V	$I_{c} = 0.5 \text{ A}^{*1}, I_{B} = 50 \text{ mA}$
E to C diode forward voltage	V <sub>D</sub>			1.2	V	I <sub>E</sub> = 0.5 A <sup>*1</sup>

Note: 1. Pulse test









Hitachi Code	TO-92 (1)
JEDEC	Conforms
EIAJ	Conforms
Weight (reference value)	0.25 g

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